



# THE PRINTED CIRCUIT BOARD COMPANY

## GreenMil Proto Express, Bangalore, India

- Up to 10 panel typ.
- Differential impedance
- 2 to 30 layers
- Lead-free process
- 3/3 Lines/spaces
- Sequential lamination
- Blind and buried vias
- Filled vias
- 24 hour - 5 day turn typ.
- Hole in pad
- Mil spec
- Metal core
- Carbon paste
- Plated edge holes
- Milled edges
- Heavy copper
- 10-40 panels typ.
- Controlled impedance
- 1 to 12 layers
- Lead-free process
- 5/5 Lines/spaces
- Mechanical drill
- Filled vias
- 5 day - 3 week turn typ.
- Mil spec
- Metal core
- Carbon paste
- Plated edge hole
- Milled edge
- Heavy copper
- Less than 2 mils(0.002") trace width and spacing
- Single and double sided
- Multilayer sequential buildup
- Blind and buried vias
- Laser-drilled hole sizes as small as 0.002"

## GreenMil Manufacturing Technologies

- Multilayer Boards, up to 30 layers and 0.250" thick
- Materials include: FR 4 (140TG,170Tg,200Tg) Polyimide, GETEK, Rogers 4003, Others Upon Request
- Controlled Impedance - (RamBus Capable)
- Blind and Buried Viad & Microvias
- Carbon Inks, Conductive Epoxies, Filled Holes
- Metal Core Boards
- Surface Finishes: HASL, White Tin, Tin-Nickel, Hard Gold, Bondable Gold,
- Immersion Gold, Immersion Silver, Entek.
- Military Certified 55110 - Renewed 2006.



POLICY

## Our Expertize

- High speed material support Megtron – 6,7 and Rogers
- Blind and buried vias
- Conductive and Non-Conductive epoxy filling for via's
- Hard gold plating for selective region
- Laser drill capability
- 6 mill mechanical drill with 4 mill drill to copper spacing
- DRC for 2.8, 3/4 mills
- Laser stack up to 24 layers
- Planting option ROHS, Silver
- Via black drilling
- PCB thickness up to 5mm

### TECHNOLOGY

	Standard	Controlled
Min Drill Size	.0059"	.004"
Aspect Ratio	10:1	20:1
Line Width & Space	.002"	.00125"
All surface finishes available		

